NuSil EPM-2420

Silicone

NuSil Technology

Message:

As a low stress alternative for electronic packaging, NuSil Technology's silicones allow the designer to choose from a unique line of silicones for various levels of packaging. We have an extensive line of encapsulants, adhesives, and greases to choose from. These include thermally and electrically conductive silicones for Thermal Interface Materials (TIM) or for EMI and RFI shielding applications. Benefits of Silicone for Electronics: Wide Operating Temperature Range of -115 °C to 250 °C Low moisture absorption, < 0.4% Typical **Corrosion Resistance** High Dielectric Strength > 500 V/mil (0.001 inch) or 20 kV/mm Fillers can be added to provide thermal and electrical conductive properties Low Modulus (Typically less than 5.5 MPa/800 psi) Stable chemical and mechanical properties when exposed to high temperatures Low Shrinkage Available as gels, elastomers, film adhesives sheeting, and greases General Purpose: Potting and Encapsulating Materials Comments: Low Viscosity, Self-leveling Adhesive to Polyester and Polyether General Information

General Information						
Features	Good Corrosion Resistance					
	Good Thermal Stability Low Moisture Absorption Low Shrinkage					
				Low Viscosity		
	Uses	Adhesives				
	Electrical/Electronic Applications					
Processing Method	Encapsulating					
	Potting					
	Potting					
	Potting					
Thermoset	Potting Nominal Value	Unit				
Thermoset Thermoset Components	-	Unit				
	-	Unit				
Thermoset Components	Nominal Value	Unit				
Thermoset Components Part A	Nominal Value Mix Ratio by Weight: 1.0	Unit				
Thermoset Components Part A Part B	Nominal Value Mix Ratio by Weight: 1.0 Mix Ratio by Weight: 1.0					
Thermoset Components Part A Part B Additional Information	Nominal Value Mix Ratio by Weight: 1.0 Mix Ratio by Weight: 1.0 Nominal Value					
Thermoset Components Part A Part B Additional Information Cure System	Nominal Value Mix Ratio by Weight: 1.0 Mix Ratio by Weight: 1.0 Nominal Value					
Thermoset Components Part A Part B Additional Information Cure System Ionic Content	Nominal Value Mix Ratio by Weight: 1.0 Mix Ratio by Weight: 1.0 Nominal Value Platinum	Unit				
Thermoset Components Part A Part B Additional Information Cure System Ionic Content CI	Nominal Value Mix Ratio by Weight: 1.0 Mix Ratio by Weight: 1.0 Nominal Value Platinum	Dunit				
Thermoset Components Part A Part B Additional Information Cure System Ionic Content CI K	Nominal Value Mix Ratio by Weight: 1.0 Mix Ratio by Weight: 1.0 Nominal Value Platinum < 2 < 1	Unit ppm ppm				

Color	Clear/Transparent	
Density	1.01	g/cm ³
Viscosity		
1	1.2	Pa·s
2	2.5	Pa·s
Curing Time (65°C)	1.0	hr
Cured Properties	Nominal Value	Unit
Shore Hardness (Shore A)	30	
Tensile Strength	2.76	MPa
Tensile Elongation at Break	150	%
NOTE		
1.	Part B	
2.	Part A	

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